

Appl. No. 09/655,893

Attorney Docket No. 10541-2085

I. Listing of Claims

1 – 13 (Cancelled)

14. (Previously Presented) A method for forming a connection within a multi-layer circuit board, said multi-layer circuit board including a first pre-circuit assembly including a conductive core member, a dielectric member which is attached to a top surface of said conductive core member, and a second pre-circuit assembly including a second core member and a first and second conductive member which are respectively attached to a top and bottom surface of said second core member, said method comprising the steps of:

selectively forming at least one hole through said first pre-circuit assembly in a location where a connection to said conductive core member is desired to be formed;

registering said second pre-circuit assembly with respect to said first pre-circuit, effective to cause a portion of said second conductive member to reside above said at least one hole;

attaching said second pre-circuit assembly to said dielectric member; and

selectively inserting a conductive material within said at least one hole, effective to connect said portion of said second conductive member to said conductive core member.



BRINKS HOFER GILSON & LIONE
PO Box 10395
Chicago, IL 60611-5599

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15. (Original) The method of claim 14 further comprising the step of: selectively etching at least a portion of said second core member.

16. (Original) The method of claim 14 wherein said conductive material comprises solder.

17. (Previously Presented) The method of claim 16 wherein said solder is selectively inserted into said at least one hole by use of a compression printing technique.

18. (Original) The method of claim 14 wherein said conductive core member is manufactured from a copper material.

19. (Previously Presented) The method of claim 14 wherein said first and said second conductive member each comprises a copper member.

20. (Previously Presented) The method of claim 14 wherein said second core member comprises an aluminum member.

21. (Previously Presented) The method of claim 14, further comprising the step of coupling an adhesive layer to the dielectric member.

22. (Previously Presented) A method for forming a connection within a multi-layer circuit board, said multi-layer circuit board including a first pre-circuit



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Chicago, IL 60611-6599

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assembly including a conductive core member, a dielectric member which is attached to a top surface of said conductive core member, and a second pre-circuit assembly including a second core member and a first and second conductive member which are respectively attached to a top and bottom surface of said second core member, said method comprising the steps of:

selectively forming at least one hole through said first pre-circuit assembly in a location where a connection to said conductive core member is desired to be formed;

registering said second pre-circuit assembly with respect to said first pre-circuit, effective to cause a portion of said second conductive member to reside above said at least one hole;

attaching said second pre-circuit assembly to said dielectric member;

selectively inserting a conductive material within said at least one hole, effective to connect said portion of said second conductive member to said conductive core member;

selectively removing areas of said second pre-circuit assembly which are disposed above said first portion of the second conductive member of said second pre-circuit assembly, thereby exposing said first portion of said second conductive member; and

deforming said first portion of said second conductive member, effective to cause said first portion of said second pre-circuit assembly to extend within said hole.



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23. (Previously Presented) The method of claim 22 wherein said first portion of said second pre-circuit assembly comprises a bridge portion.

24. (Previously Presented) The method of claim 22 wherein said first portion of said second pre-circuit assembly comprises a tab portion.

25. (Previously Presented) The method of claim 22 further comprising the step of selectively etching at least a portion of said second core member.

26. (Previously Presented) The method of claim 22 wherein said conductive material comprises solder.

27. (Previously Presented) The method of claim 22 wherein said first and said second conductive member each comprises a copper member.

28. (Previously Presented) The method of claim 22 wherein said second core member comprises an aluminum member.

29. (Previously Presented) The method of claim 22, further comprising the step of coupling an adhesive layer to the dielectric member.



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